

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1 to 8 (Canceled).

1 9. (Currently Amended): A method comprising the steps of:  
2 providing a printed circuit board having a circuit trace thereon and a solder mask over the  
3 circuit trace;  
4 testing the circuit trace;  
5 determining that the tested circuit trace contains a defect;  
6 removing the solder mask from the printed circuit board using an ultra violet laser after  
7 the determining step, to expose the circuit trace without damaging the circuit trace; and  
8 performing failure analysis on the circuit trace of the printed circuit board, thereby  
9 determining a cause of the defect.

1 10. (Original): The method of claim 8, wherein the ultraviolet laser has a wavelength of from  
2 about 3 nanometers to about 400 nanometers.

1 11. (Original): The method of claim 9, wherein the ultraviolet laser has a wavelength from  
2 the group consisting of 355 nanometers and 266 nanometers.

1 12. (Original): The method of claim 9, wherein the ultraviolet laser is one of the group  
2 consisting of a solid state laser, a gas laser, a dye laser, and an excimer laser.

1 13. (Original): The method of claim 12, wherein the ultraviolet laser is a yttrium aluminum  
2 garnet laser.

1 14. (Original): The method of claim 9, wherein the solder mask comprises an organic  
2 compound.

1 15. (Original): The method of claim 9, wherein the solder mask comprises a thermosetting  
2 resin.

1 16. (Original): The method of claim 15, wherein the solder mask comprises a film selected  
2 from the group consisting of polyimide and cyanate ester resins and a dual solution photo-curing  
3 type material containing an unsaturated resin that includes carboxylic acid and a polyepoxy  
4 compound.

1 17. (Withdrawn): A printed circuit board suitable for failure analysis, the printed circuit  
2 board being prepared by a method comprising the steps of:  
3 providing a printed circuit board having a circuit trace thereon and a solder mask over the  
4 circuit trace;  
5 removing the solder mask from the printed circuit board using an ultra violet laser, to  
6 expose the circuit trace without damaging the circuit trace, thereby readying the printed circuit  
7 board for performing failure analysis on the circuit trace thereof.

1 18. (Withdrawn): The printed circuit board of claim 17, wherein the ultraviolet laser has a  
2 wavelength of from about 3 nanometers to about 400 nanometers.

1 19. (Withdrawn): The printed circuit board of claim 17, wherein the ultraviolet laser has a  
2 wavelength from the group consisting of 355 nanometers and 266 nanometers.

1 20. (Withdrawn): The printed circuit board of claim 17, wherein the ultraviolet laser is one of  
2 the group consisting of a solid state laser, a gas laser, a dye laser, and an excimer laser.

1 21. (Withdrawn): The printed circuit board of claim 20, wherein the ultraviolet laser is a  
2 yttrium aluminum garnet laser.

1 22. (Withdrawn): The printed circuit board of claim 17, wherein the solder mask comprises  
2 an organic compound.

1 23. (Withdrawn): The method of claim 17, wherein the solder mask comprises a  
2 thermosetting resin.

1 24. (Withdrawn): The printed circuit board of claim 23, wherein the solder mask comprises a  
2 film selected from the group consisting of polyimide and cyanate ester resins and a dual solution  
3 photo-curing type material containing an unsaturated resin that includes carboxylic acid and a  
4 polyepoxy compound.

1 25. (Withdrawn): A device suitable for failure analysis, the device being prepared by a  
2 method comprising the steps of:  
3 providing a substrate having a circuit trace thereon and a solder mask over the circuit  
4 trace;  
5 removing the solder mask from the substrate using an ultra violet laser, to expose the  
6 circuit trace without damaging the circuit trace, thereby readying the substrate for performing  
7 failure analysis on the circuit trace thereof.

1 26. (Withdrawn): The device of claim 25, wherein the ultraviolet laser has a wavelength of  
2 from about 3 nanometers to about 400 nanometers.

1 27. (Withdrawn): The device of claim 25, wherein the ultraviolet laser has a wavelength from  
2 the group consisting of 355 nanometers and 266 nanometers.

1 28. (Withdrawn): The device of claim 25, wherein the ultraviolet laser is one of the group  
2 consisting of a solid state laser, a gas laser, a dye laser, and an excimer laser.

1 29. (Withdrawn): The device of claim 28, wherein the ultraviolet laser is a yttrium aluminum  
2 garnet laser.

1 30. (Withdrawn): The device of claim 25, wherein the solder mask comprises an organic  
2 compound.

1 31. (Withdrawn): The device of claim 25, wherein the solder mask comprises a thermosetting  
2 resin.

1 32. (Withdrawn): The device of claim 25, wherein the solder mask comprises a film selected  
2 from the group consisting of polyimide and cyanate ester resins and a dual solution photo-curing  
3 type material containing an unsaturated resin that includes carboxylic acid and a polyepoxy  
4 compound.

1 33. (New): The method of claim 9, wherein the failure analysis includes visually inspecting  
2 the circuit trace.

1 34. (New): The method of claim 9, wherein the failure analysis includes performing a  
2 scanning electron microscope inspection of the circuit trace.